

Reasons

1. The invention pertaining to the following claims of this application is based on the inventions that are described in the following publications which were distributed within Japan and abroad prior to that application and a patent cannot be granted according to the provisions of Patent Law Article No. 29 Item No. 2 since there is the possibility of being easily invented by a person having general knowledge in the technological field that is affiliated with the invention prior to the application.

Record (Refer to the List of Cited Documents for the Cited Documents)

- Claims 1~6
- Cited Documents 1~2
- Remarks

A 2nd conductive section being one formed from a solder bump that connects to a 1st conductive section is described in Citation 2, and utilization of the above-mentioned construction in a semiconductor device that has an insulating layer and an insulating resin layer as described in Citation 1 can be recognized as easily obtained by one skilled in the art.

2. The invention pertaining to the following claims of this application has the patent application prior to that application with the same invention that is described in the Figures or Specifications that are initially attached to the application of the following patent application which was done by laid-open application of application publication after that application; also, the inventor of this application is not the same person that invented the aforementioned pertaining to the patent application prior to that application at the time of this application and that applicant is not the same as the applicant of the aforementioned patent application, thus a patent cannot be granted according to the provisions of Patent Law Article No. 29 [No.] 2.

Record (Refer to the List of Cited Documents for the Cited Documents)

- Claims 1~6
- Cited Documents 3~8

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List of Cited Documents

1. Publication of Japanese Laid-Open Patent No. H9-64049

2. Publication of Japanese Laid-Open Patent No. H9-213830
 3. Japanese Patent Application No. H11-165305
(Laid-Open Patent No. 2000-353762)
 4. Japanese Patent Application No. H11-308573
(Laid-Open Patent No. 2001-127095)
 5. Japanese Patent Application No. H10-198127
(Laid-Open Patent No. 2000-22052)
 6. Japanese Patent Application No. H11-249987
(Laid-Open Patent No. 2001-77142)
 7. Japanese Patent Application No. H11-291472
(Laid-Open Patent No. 2001-110828)
 8. Japanese Patent Application No. H11-113658
(Laid-Open Patent No. 2000-306939)
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